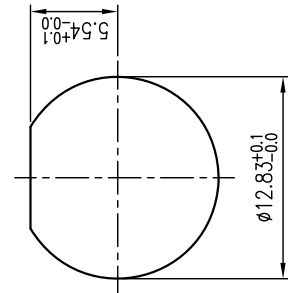
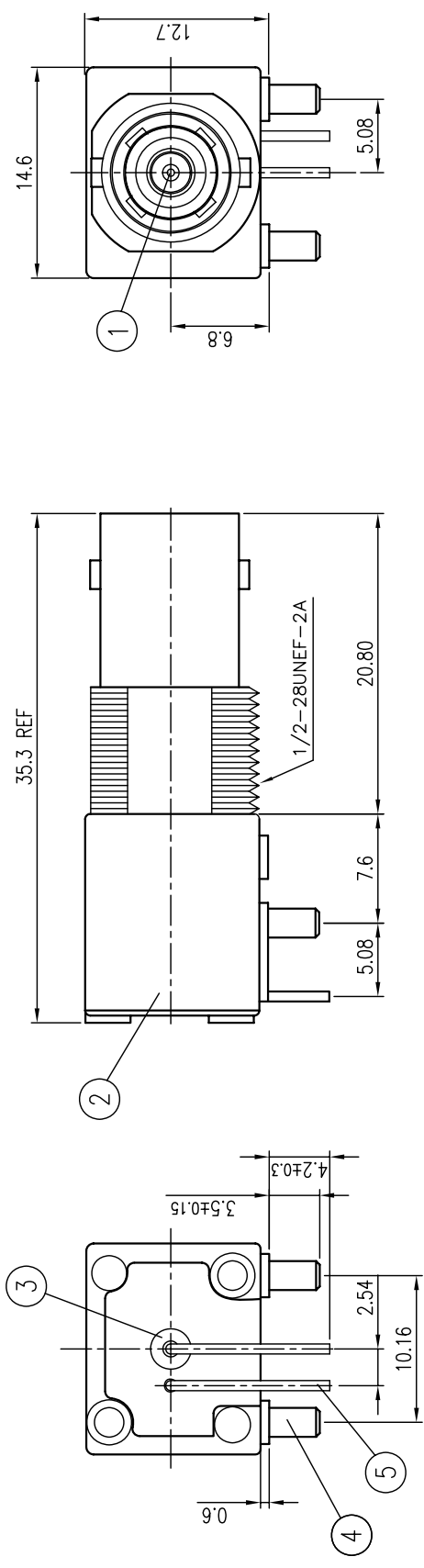


This document is the property of Amphenol Corporation and is delivered on the express condition that it is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document. The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2002/95/EE for RoHS compliant.



RECOMMENDED PC BOARD LAYOUT
WITHOUT MOUNTING POSTS

RECOMMENDED MOUNTING HOLE
MAXIMUM PANEL THICKNESS: 5.5MM

- MATERIAL & FINISH**
- ① CENTER CONTACT : BRONZE, GOLD PLATING / TAIL: TIN PLATING
 - ② BODY : ZINC ALLOY, NICKEL PLATING
 - ③ INSULATOR : PE-606
 - ④ MOUNTING POST : BRASS, TIN PLATING
 - ⑤ SOLDER TAIL : BRASS WIRE, TIN PLATING

SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	08/09/2005	Henry Ko
B	NE-05343	CHANGED MATERIAL FROM TEFLON TO PE-606	10/20/2005	Henry Ko
C	NE-11009	MODIFY DRAWING	01/21/2011	Roger Tsai

TOLERANCE	APPROVALS	DATE	TITLE			
X X.X X.XX X.XXX	ROG TSOI	01/21/2011	BNC BULKHEAD RECE., R/A PCB MOUNT LOW PROFILE, 50 OHMS			
ANGULAR ±1°	AQUA CHOU	01/21/2011				
UNLESS OTHERWISE SPECIFIED	ROG TSOI	01/21/2011				
	DWG TYPE	PROJECT CODE	UNIT	SCALE	SHEET	REV.
	CUST DWG	RFM	mm	NA	1 OF 1	C

Amphenol®
Amphenol Corporation
Amphenol Taiwan Corporation

PART No. G11A0361EU
DWG No. G11A0361EU